

General Description

The MAX9179 is a quad low-voltage differential signaling (LVDS) line receiver designed for applications requiring high data rates, low power dissipation, and noise immunity. The receiver accepts four LVDS input signals and translates them to 3.3V LVCMOS output levels at speeds up to 400Mbps. The receiver features built-in hysteresis, which improves noise immunity and prevents multiple switching on slow transitioning inputs.

The device supports a wide 0.038V to 2.362V commonmode input voltage range, allowing for ground potential differences and common-mode noise between the driver and the receiver. A fail-safe circuit sets the output high when the input is open, undriven and shorted, or undriven and terminated. Common enable inputs control the highimpedance outputs.

The MAX9179 has a flow-through pinout for easy PC board layout, and is pin compatible with the MAX9121 and the DS90LV048A with the additional features of high ESD tolerance and built-in hysteresis.

The MAX9179 operates from a single 3.3V supply, and is specified for operation from -40°C to +85°C. The device is offered in 16-pin TSSOP and thin QFN packages.

Applications

Laser Printers

Digital Copiers

Cell-Phone Base Stations

Telecom Switching Equipment

LCD Displays

Network Switches/Routers

Backplane Interconnect

Clock Distribution

Features

- ♦ Guaranteed 400Mbps Data Rate
- ♦ 50mV (typ) Hysteresis
- ♦ Overshoot/Undershoot Protection (-1.0V or VCC + 1.0V) on Enables
- ♦ IEC61000-4-2 Level 4 ESD Tolerance
- ♦ AC Specifications Guaranteed with |VID| = 100mV
- ♦ Single 3.3V Supply
- ♦ Fail-Safe Circuit
- **♦** Flow-Through Pinout Simplifies PC Board Layout **Reduces Crosstalk**
- **♦ Low-Power CMOS Design**
- ♦ Conforms to ANSI TIA/EIA-644 LVDS Standard
- ♦ High-Impedance Inputs when Powered Off
- ♦ Pin Compatible with the MAX9121 and the **DS90LV048A**
- **♦ Small Thin QFN Package Available**

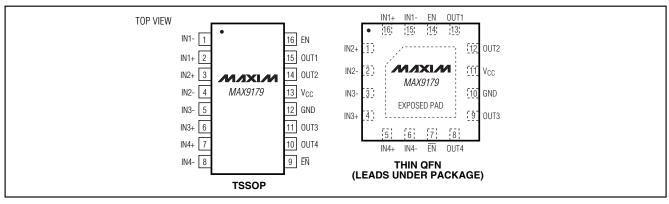
Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX9179EUE	-40°C to +85°C	16 TSSOP
MAX9179ETE*	-40°C to +85°C	16 Thin QFN-EP**

^{*}Future product—contact factory for availability.

Functional Diagram appears at end of data sheet.

Pin Configurations



MIXIM

Maxim Integrated Products 1

^{**}EP = Exposed paddle.

ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	0.3V to +4.0V	Storage Temperature Range	-65°C to +150°C
IN_+, IN to GND	0.3V to +4.0V	ESD Protection	
EN, EN to GND	1.4V to (V _{CC} + 1.4V)	Human Body Model ($R_D = 1.5k\Omega$, $C_S = 100pl$	F)
OUT_ to GND	0.3V to (V _{CC} + 0.3V)	(IN_+, IN)	±16kV
Continuous Power Dissipation (Ta	$A = +70^{\circ}C$	IEC61000-4-2 (R _D = 330 Ω , C _S = 150pF) (IN_	+, IN)
16-Pin TSSOP (derate 9.4mW/°	C above +70°C)755mW	Contact Discharge	±8kV
16-Pin Thin QFN (derate 16.9m	W/°C	Air-Gap Discharge	±15kV
above +70°C)	1349mW	Soldering Temperature (soldering, 10s)	+300°C
Junction Temperature	+150°C		

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 3.0V \text{ to } 3.6V, \text{ differential input voltage } |V_{ID}| = 0.075V \text{ to } 1.2V, \text{ input common-mode voltage } |V_{CM}| = |V_{ID}/2| \text{ to } 2.4V - |V_{ID}/2|, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } |V_{CC}| = 3.3V, |V_{ID}| = 0.2V, |V_{CM}| = 1.2V, T_A = +25^{\circ}\text{C}.) \text{ (Notes 1, 2)}$

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
INPUTS (IN_+, IN)							
Differential Input High Threshold	V _{TH}	Figure 1			25	75	mV
Differential Input Low Threshold	V _{TL}	Figure 1		-75	-25		mV
Hysteresis	V _{TH} - V _{TL}	Figure 1			50		mV
Input Current	I _{IN+} , I _{IN-}			-20		+20	μΑ
Power-Off Input Current	IOFF+, IOFF-	V _{CC} = 0V		-20		+20	μΑ
Fail-Safe Input Resistor 1	R _{IN1}	$V_{CC} = 3.6V \text{ or } 0$	OV, Figure 2	40		65	kΩ
Fail-Safe Input Resistor 2	R _{IN2}	$V_{CC} = 3.6V \text{ or } 0$	OV, Figure 2	280		455	kΩ
OUTPUTS (OUT_)		•					
Output High Voltage	V _{OH}	I _{OH} = -4.0mA	Open, undriven short, or undriven parallel termination	V _{CC} - 0.2	V _{CC} - 0.1		V
			$V_{ID} = +50mV$				
Output Low Voltage	Vol	$I_{OL} = 4.0 \text{mA}, V$	$I_{OL} = 4.0 \text{mA}, V_{ID} = -50 \text{mV}$		0.1	0.25	V
Output Short-Circuit Current	los	Enabled, V _{ID} = +50mV, V _{OUT} = 0 (Note 3)		-40	-70	-120	mA
Output High-Impedance Current	loz	Disabled, V _{OUT} = 0 or V _{CC}		-1.0		+1.0	μΑ
ENABLE INPUTS (EN, EN)							
Input High Voltage	V _{IH}			2.0		V _{CC} + 1.0	V
Input Low Voltage	V _{IL}			-1.0		+0.8	V
		-1.0V ≤ EN, EN	-1800		+10		
Input Current	I _{IN}	$OV \le EN, \overline{EN} \le V_{CC}$		-20		+20	μΑ
		V _{CC} ≤ EN, EN	≤ V _{CC} + 1.0V	-10		+1800	
POWER SUPPLY							
Supply Current	Icc	Enabled, inputs	s open		10.4	15	mA
Disabled Supply Current	Iccz	Disabled, input	ts open		0.6	1.0	IIIA

AC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 3.0 \text{V to } 3.6 \text{V}, C_L = 15 \text{pF}, \text{ differential input voltage } |V_{ID}| = 0.1 \text{V to } 1.2 \text{V}, \text{ input common-mode voltage } |V_{CM} = |V_{ID}/2|, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = 3.3 \text{V}, |V_{ID}| = 0.2 \text{V}, V_{CM} = 1.2 \text{V}, T_A = +25 ^{\circ}\text{C}.)$ (Notes 4, 5, 6)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Differential Propagation Delay High to Low	tPHLD	Figures 3, 4	2.0	2.6	4.6	ns
Differential Propagation Delay Low to High	tPLHD	Figures 3, 4	2.0	2.52	4.6	ns
D:((): 1D 1 O		V _{ID} = 0.1V to 0.15V			700	
Differential Pulse Skew I tphlD - tplhD I (Note 7)	tskD1	V _{ID} = 0.15V to 0.2V			400	ps
TIPALD TPLADT (Note 1)		V _{ID} = 0.2V to 1.2V		80	300	
Differential Channel-to-Channel		V _{ID} = 0.1V to 0.15V			900	
Skew, Same Part	tskD2	V _{ID} = 0.15V to 0.2V			600	ps
(Note 8)		V _{ID} = 0.2V to 1.2V		120	400	ps ns
Differential Part-to-Part Skew (Note 9)	tskD3				2.0	ns
Differential Part-to-Part Skew (Note 10)	tskD4				2.6	ns
Rise Time	tTLH			0.77	1.4	ns
Fall Time	tTHL			0.74	1.4	ns
Disable Time High to Z	tphz	$R_L = 2k\Omega$, Figures 5, 6 (Note 11)		10.6	14	ns
Disable Time Low to Z	tpLZ	$R_L = 2k\Omega$, Figures 5, 6 (Note 11)		11	14	ns
Enable Time Z to High	tpzh	$R_L = 2k\Omega$, Figures 5, 6 (Note 11)		4.8	14	ns
Enable Time Z to Low	tpzL	$R_L = 2k\Omega$, Figures 5, 6 (Note 11)		4.8	14	ns
Maximum Operating Frequency	fMAX	All channels switching, C _L = 15pF, V _{OL} (max) = 0.25V, V _{OH} (min) = V _{CC} - 0.2V, 44% < duty cycle < 56%	200	250		MHz

- **Note 1:** Maximum and minimum limits over temperature are guaranteed by design and characterization. Parts are production tested at $T_A = +25$ °C.
- Note 2: Current into a pin is defined as positive. Current out of a pin is defined as negative. All voltages are referenced to ground except V_{TH}, V_{TL}, and V_{ID}.
- **Note 3:** Short one output at a time.
- Note 4: AC parameters are guaranteed by design and characterization. Limits are set at ±6 sigma.
- Note 5: C_L includes scope probe and test jig capacitance.
- **Note 6:** Pulse generator differential output for all tests (unless otherwise noted): $t_R = t_F < 1$ ns (0% to 100%), frequency = 100MHz, 50% duty cycle.
- Note 7: t_{SKD1} is the magnitude of the difference of the differential propagation delays in a channel. t_{SKD1} = I t_{PHLD} t_{PLHD} I.
- Note 8: tskD2 is the magnitude of the difference of the tpLHD or tpHLD of one channel and the tpLHD or tpHLD of the other channel on the same part.
- Note 9: t_{SKD3} is the magnitude of the difference of any differential propagation delays between parts at the same V_{CC} and within 5°C of each other.
- **Note 10:** ts_{KD4} is the magnitude of the difference of any differential propagation delays between parts operating over the rated supply and temperature ranges.
- **Note 11:** Pulse generator output for tpHz, tpLz, tpzH, and tpzL tests: $t_R = t_F = 1.5$ ns (0.2V_{CC} to 0.8V_{CC}), 50% duty cycle, $v_{OH} = v_{CC} + 1.0$ V settling to v_{CC} , $v_{OL} = -1.0$ V settling to 0, frequency = 1MHz.

V_{OUT} V_{TL} V_{TH} V_{ID} -V_{ID} -V_{ID}

Figure 1. Input Thresholds and Hysteresis

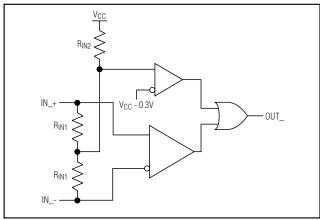


Figure 2. Fail-Safe Input Circuit

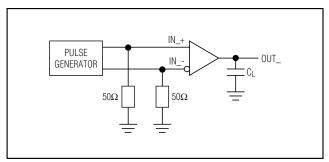


Figure 3. Propagation Delay and Transition Time Test Circuit

Test Circuits/Timing Diagrams

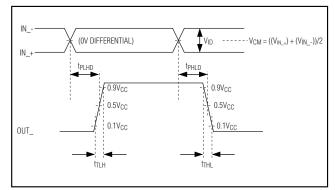


Figure 4. Propagation Delay and Transition Time Waveforms

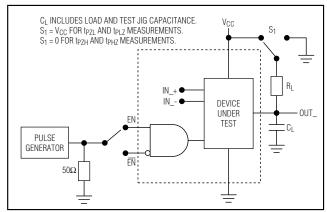


Figure 5. High-Impedance Delay Test Circuit

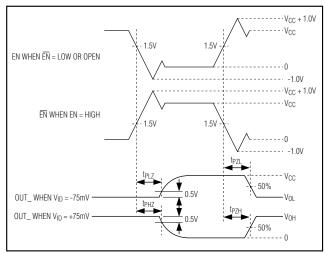
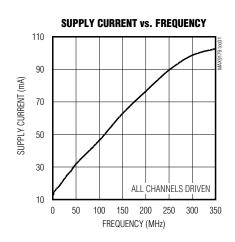
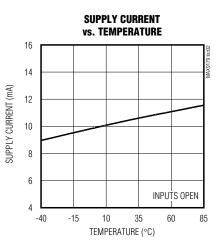


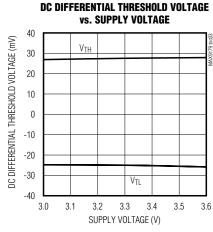
Figure 6. High-Impedance Delay Waveforms

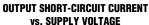
Typical Operating Characteristics

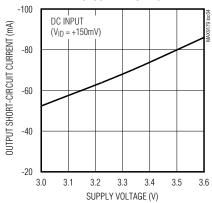
 $(V_{CC} = 3.3V, V_{CM} = 1.2V, |V_{ID}| = 0.15V, C_L = 15pF, f = 100MHz, T_A = +25^{\circ}C, unless otherwise noted.)$



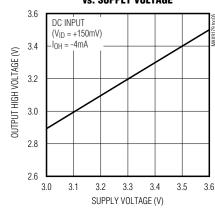




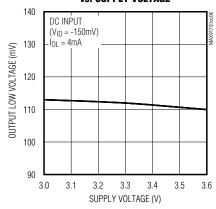




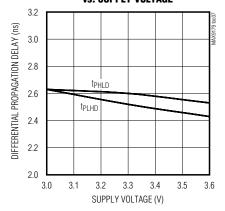




OUTPUT LOW VOLTAGE vs. SUPPLY VOLTAGE

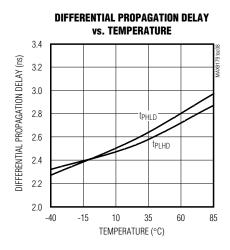


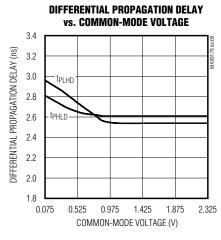
DIFFERENTIAL PROPAGATION DELAY vs. SUPPLY VOLTAGE

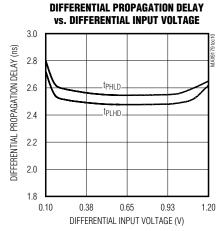


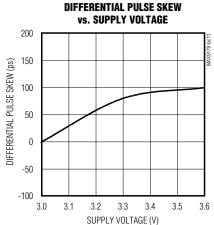
Typical Operating Characteristics (continued)

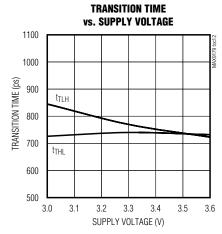
 $(V_{CC} = 3.3V, V_{CM} = 1.2V, |V_{ID}| = 0.15V, C_L = 15pF, f = 100MHz, T_A = +25^{\circ}C, unless otherwise noted.)$

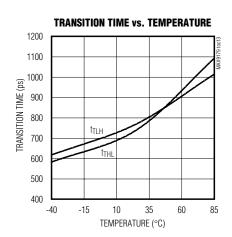


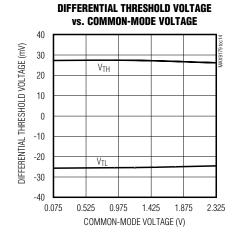












Pin Description

PI	N	NAME	FUNCTION					
TSSOP	QFN	NAME	TONOTION					
1	15	IN1-	Inverting LVDS Input 1					
2	16	IN1+	Noninverting LVDS Input 1					
3	1	IN2+	Noninverting LVDS Input 2					
4	2	IN2-	Inverting LVDS Input 2					
5	3	IN3-	Inverting LVDS Input 3					
6	4	IN3+	Noninverting LVDS Input 3					
7	5	IN4+	Noninverting LVDS Input 4					
8	6	IN4-	Inverting LVDS Input 4					
9	7	ĒN	Enable Complementary Input. The outputs are active when EN = high and $\overline{\text{EN}}$ = low or open. For all other combinations of EN and $\overline{\text{EN}}$, the outputs are disabled and in high impedance.					
10	8	OUT4	LVCMOS/LVTTL Output 4					
11	9	OUT3	LVCMOS/LVTTL Output 3					
12	10	GND	Ground					
13	11	Vcc	Power-Supply Input. Bypass V _{CC} to GND with 0.1µF and 0.001µF ceramic capacitors.					
14	12	OUT2	LVCMOS/LVTTL Output 2					
15	13	OUT1	LVCMOS/LVTTL Output 1					
16	14	EN	Enable Input. The outputs are active when EN = high and $\overline{\text{EN}}$ = low or open. For all other combinations of EN and $\overline{\text{EN}}$, the outputs are disabled and in high impedance.					
_	EP	Exposed Pad	Exposed Pad. Connect to ground.					

Table 1. Functional Table

ENABLES		INPUTS	OUTPUT
EN	ĒN	(IN_+) - (IN)	OUT_
		≥ +75mV	Н
Н	L or open	≤ -75mV	Ш
		Open, undriven short, or undriven terminated	Н
	ombinations le inputs	X	Z

H = High logic level

L = Low logic level

X = Don't care

Z = High impedance

Detailed Description

The LVDS is a signaling method intended for point-to-point communication over a controlled-impedance medium as defined by the ANSI TIA/EIA-644 and IEEE 1596.3 standards.

The MAX9179 is a quad LVDS line receiver with built-in hysteresis, intended for high-speed, point-to-point, low-power applications. The receiver accepts four LVDS input signals and translates them to 3.3V LVCMOS out-put levels at speeds up to 400Mbps over controlled-impedance media of 100Ω . The hysteresis improves noise immunity and prevents multiple switching due to noise on slow input transitions at the end of a long cable.

The receiver is capable of detecting differential signals as low as 75mV and as high as 1.2V within a 0 to 2.4V input voltage range. The 250mV to 450mV differential output of an LVDS driver is nominally centered on a 1.2V offset. This offset, coupled with the receiver's 0 to 2.4V input voltage range, allows an approximate ±1V shift in the signal (as seen by the receiver). This allows for a difference in ground references of the transmitter and the receiver, the common-mode effects of coupled noise, or both. The LVDS standards specify an input voltage range of 0 to 2.4V referenced to receiver ground.

Hysteresis

The MAX9179 incorporates hysteresis of 50mV (typ), which rejects noise and prevents false switching during low-slew-rate transitions at the end of a long cable. The receiver typically switches at 25mV above or below V_{ID} = 0V (Figure 1). The hysteresis is designed to be symmetrical around V_{ID} = 0V for low pulse distortion (see the *Typical Operating Characteristics*).

Input Fail-Safe

The fail-safe feature of the MAX9179 sets the output high when the differential input is:

- Open
- · Undriven and shorted
- Undriven and terminated

Without a fail-safe circuit, when the input is undriven, noise at the input may switch the output and it may appear to the system that data is being sent. Open or undriven terminated input conditions can occur when a cable is disconnected or cut, or when a driver output is in high impedance. A shorted input can occur because of a cable failure.

When the input is driven with a differential signal of $IV_{ID}I = 75 \text{mV}$ to 1.2V within a voltage range of 0 to 2.4V, the fail-safe circuit is not activated. If the input is open, undriven and shorted, or undriven and terminated, an internal resistor in the fail-safe circuit pulls both inputs above V_{CC} - 0.3V, activating the fail-safe circuit and forcing the output high (Figure 2).

Overshoot and Undershoot Voltage Protection

The MAX9179 is designed to protect the enable inputs (EN and $\overline{\text{EN}}$) against latchup due to transient overshoot and undershoot voltage. If the enable input voltage goes above VCC or below GND by up to 1V, an internal circuit clamps and limits input current to 1.8mA.

Applications Information

Power-Supply Bypassing

Bypass the V_{CC} pin with high-frequency surface-mount ceramic $0.1\mu F$ and $0.001\mu F$ capacitors in parallel as close to the device as possible, with the smaller valued capacitor closest to V_{CC}.

Differential Traces

Input trace characteristics affect the performance of the MAX9179. Use controlled-impedance differential traces (100 Ω is typical). To reduce radiated noise and ensure that noise couples as common mode, route the differential input signals within a pair close together. Reduce skew by matching the electrical length of the signal paths making up the differential pair. Excessive skew can result in a degradation of magnetic field cancellation. Maintain a constant distance between the differential traces to avoid discontinuities in differential impedance. Minimize the number of vias to further prevent impedance discontinuities.

Cables and Connectors

Interconnect for LVDS typically has a controlled differential impedance of 100Ω . Use cables and connectors that have matched differential impedance to minimize impedance discontinuities. Avoid the use of unbalanced cables such as ribbon or simple coaxial cable. Balanced cables such as twisted pair offer superior signal quality and tend to generate less EMI due to magnetic field canceling effects. Balanced cables pick up noise as common mode, which is rejected by the LVDS receiver.

Termination

The MAX9179 requires external termination resistors. The input termination resistor used on each active channel should match the differential impedance of the transmission line. Place the termination resistor as close to the MAX9179 receiver input as possible. Use 1% surface-mount resistors.

Board Layout

Keep the LVDS input and LVCMOS output signals separated from each other to reduce crosstalk; 180 degrees of separation between LVDS inputs and LVCMOS outputs is recommended. Because there are leads on all sides, this separation requires special attention when laying out traces for the QFN package.

A four-layer printed circuit board with separate layers for power, ground, LVDS inputs, and single-ended logic signals is recommended. Separate the LVDS signals from the single-ended signals with power and ground planes for best results.

IEC 61000-4-2 Level 4 ESD Protection

The IEC 61000-4-2 standard (Figure 7) specifies ESD tolerance for electronic systems. The IEC61000-4-2 model specifies a 150pF capacitor that is discharged into the device through a 330 Ω resistor. The MAX9179 LVDS inputs are rated for IEC61000-4-2 level 4 (±8kV Contact Discharge and ±15kV Air-Gap Discharge). The Human Body Model (HBM) (Figure 8) specifies a 100pF capacitor that is discharged into the device through a 1.5k Ω resistor. The IEC 61000-4-2 discharges higher peak current and more energy than the HBM due to the lower series resistance and larger capacitor.

Chip Information

TRANSISTOR COUNT: 1173

PROCESS: CMOS

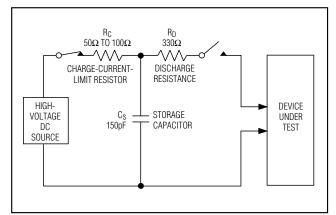


Figure 7. IEC61000-4-2 Test Model

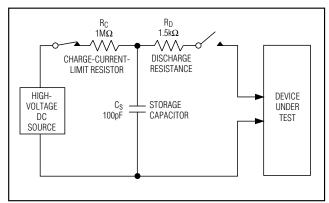
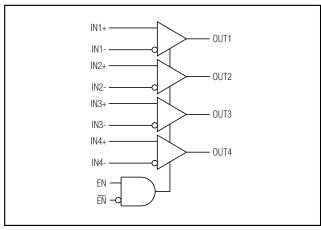


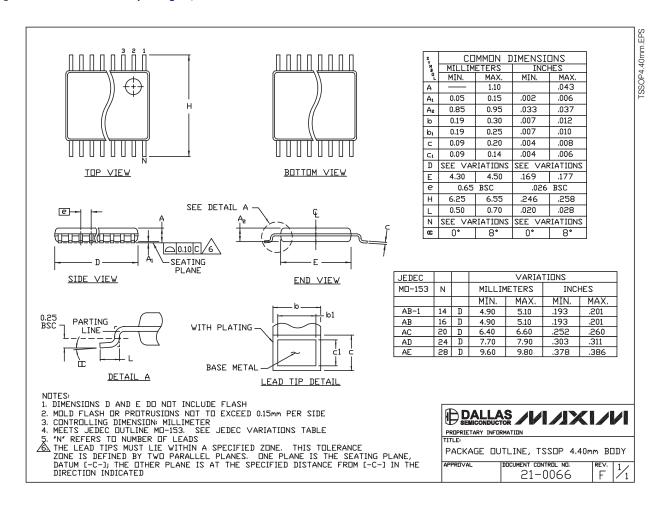
Figure 8. Human Body Test Model

Functional Diagram



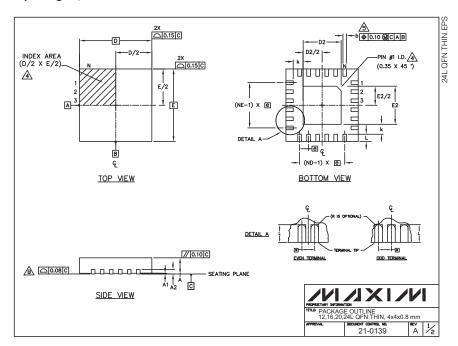
Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



					COMM	ON DI	MENS	SIDNS					
PKG	1	2L 4×4		1	6L 4×4	ŀ	2	OL 4×4	1	24L 4x4			
REF.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	
A1	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	0.0	0.02	0.05	
A2	0.20 REF 0.20			0.20 REF		0.20 REF			0.20 REF				
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	
D	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	
E	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	
e		0.80 BS0	.	0.65 BSC.		0.50 BSC.		0.50 BSC.					
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-	-	
L	0.45	0.55	0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	
N		12			16			20		24			
ND		3		4			5		6				
NE		3		4			5		6				
Jedec Vor.		WGGB			WGGC			WGGD-	VGGD-1		WGGD-2		

EXPOSED PAD VARIATIONS							
PKG.		DS		ES			
CODES	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	
T1244-2	1.95	2.10	2.25	1.95	2.10	2.25	
T1644-2	1.95	2.10	2.25	1.95	2.10	2.25	
T2044-1	1.95	2.10	2.25	1.95	2.10	2.25	
T2444-1	2.45	2.60	2.63	2.45	2.60	2.63	

- DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES. N IS THE TOTAL NUMBER OF TERMINALS.
- THE TERMINAL \$1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO LESS 95-1 SPP-012. DETAILS OF TERMINAL \$1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. HE TERMINAL \$1 IDENTIFIER MAY BE EITHER A MOULD OR MAYED FEATURE.
- (£) DIMENSION 6 APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.
- ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- AWING CONFORMS TO JEDEC MO220.



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